IN THE CLAIMS:

Claims 2-8, 10, and 12-17 have been amended herein. All of the pending claims 1 through 17 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Original) A semiconductor device formed by a laser etching process comprising:
providing a substrate having a surface;
forming resist on at least a portion of the surface; and
etching the resist from the surface of the substrate using a laser.

2. (Currently Amended) The method according to claim 1, wherein ~~said~~ the laser comprises a laser associated with an automolding system.

3. (Currently Amended) The method according to claim 1, wherein ~~said~~ the laser includes one of an Nd:YAG laser and an excimer laser.

4. (Currently Amended) The method according to claim 1, wherein ~~said~~ the substrate comprises a ball-grid-array substrate.

5. (Currently Amended) The method according to claim 1, further comprising a vision system for detecting ~~resist~~ the resist.

6. (Currently Amended) The method according to claim 5, wherein ~~said~~ the vision system comprises:
providing a laser scanning system; and
detecting changes in a pattern of the substrate.

7. (Currently Amended) A method of enhancing the adhesion of a compound to a surface of a substrate comprising:
providing ~~said~~ the substrate having ~~said~~ the surface; and
roughening the surface of the substrate.

8. (Currently Amended) The method according to claim 7, wherein ~~said~~ roughening comprises removing contamination and foreign particles from ~~said~~ the surface of the substrate.

9. (Original) An automolding system comprising:
providing a substrate having a surface;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

10. (Currently Amended) The automolding system of claim 9, wherein ~~said~~ the laser comprises one of an Nd:YAG laser and an excimer laser.

11. (Original) The automolding system of claim 9, further comprising:
placing the substrate in a mold; and
encapsulating the substrate.

12. (Currently Amended) A semiconductor device formed by a laser etching process on a substrate having a surface comprising:
forming resist on at least a portion of the surface; and
etching the resist from the at least a portion of the surface of the substrate using a laser.

13. (Currently Amended) The method according to claim 12, wherein ~~said~~ the laser comprises a laser associated with an automolding system.

14. (Currently Amended) The method according to claim 12, wherein ~~said~~ the laser includes one of an Nd:YAG laser and an excimer laser.

15. (Currently Amended) The method according to claim 12, wherein ~~said~~ the substrate comprises a ball-grid-array substrate.

16. (Currently Amended) The method according to claim 12, further comprising a vision system for detecting ~~resist~~ the resist.

17. (Currently Amended) The method according to claim 16, wherein ~~said~~ the vision system comprises:
providing a laser scanning system; and
detecting changes in a pattern of the substrate.